

Ref No: CMEB-SA-1234-19

Date: 06-May-19

To: M/s _____

Fax No: _____

Subject: Quotation for Pull Tester

We intend to purchase goods detailed as on attached annexure. Kindly send us your best offer in accurate with following General Conditions as stated below :-

General Conditions:

- a) Submission of Quotation: Quotation may be sent immediately through Fax or Courier but Original Proforma Invoice along with detailed technical brochures / literature must reach us by mail before the last date mentioned below.
- a) Currency: Quotation should be in **RMB**.
- b) Last Date of Quotation: 27-May-19
- c) Validity: At least 90 days.
- d) Prices Basis: Firm and Fix C&F Prices
- e) Payment Mode:
 - We accept payment through L/C with condition that all domestic bank charges will be borne by us while all bank in beneficiary's country including all L/C conformation (if desired by the supplier) charges will be borne by the beneficiary, OR payment may be made against shipping documents OR after delivery of goods (in case of small value).
 - We accept Pre-payment only against unconditional & irrevocable Bank Guarantee through First Class Bank.

Note:

While arranging offer following must be complied with:-

- a. Make: Semi-automatic Pull Tester Model Dage Series 4000 WP 100 or Equivalent.
- a. Supplier may other make/model of equivalent specifications.
- b. Quotation must be accompanied with detailed technical literature/brochure, Service & operational manual etc.

Sr. #	Description	Unit	Qty.
	<p>Semi-automatic Pull Tester Model Dage Series 4000 WP 100 OR Equivalent X, Y and Z motorized axis 450mm X travel linear encoder stage 450mm Y travel linear encoder stage X, Y Resolution < 1µm Z Resolutions: ±0.1µm Test type: wire pull, shear and tweezers test Operating mode: manual and semi-automatic Automatic report generator and data storage.</p> <p>Accessories</p> <ol style="list-style-type: none"> 1. Standards Accessories 2. Semiconductor multi-function cartridges P100 (Hook should be included) (Wire pull range: from 0 to 100 g on wires from 18 to 75 µm) 3. Intel 8th Generation Processor based PC having Internal Windows® 10 with Bond Test Manager, Mouse, Keyboard and 21 Inch color HD LED Monitor 4. Image Capture Camera 5. 2nd Vertical Camera of Choice (Alignment Or Field Of View) 6. Camera Assist Automation Software 7. Wafer Map Software 8. Leica S6 microscope with 20x eyepieces, focusing arm, 6.3x to 40x magnification 9. Installation and Training should be included 	No.	01

